



PATENT

ASSIGNMENT

WHEREAS, I/WE

(1) Keita ISHIDUKA, a Japanese citizen, residing at c/o TOKYO OHKA KOGYO CO., LTD., 150,  
Nakamaruko, Nakahara-ku, Kawasaki-shi, Kanagawa 211-0012 Japan

(2) Kotaro ENDO, a Japanese citizen, residing at c/o TOKYO OHKA KOGYO CO., LTD., 150,  
Nakamaruko, Nakahara-ku, Kawasaki-shi, Kanagawa 211-0012 Japan

hereinafter referred to as Assignor (collectively if more than one inventor is listed above), have invented certain new and useful improvements in MATERIAL FOR FORMING RESIST PROTECTION FILMS AND METHOD FOR RESIST PATTERN FORMATION WITH THE SAME, the specification of which:

- (a)  was executed on even date herewith;
- (b)  was filed on \_\_\_\_\_ as  Application No. 0 / \_\_\_\_\_ or  Express Mail No., as Application No. not yet known \_\_\_\_\_ and was amended on \_\_\_\_\_ (if applicable); or
- (c)  was described and claimed in PCT International Application No. PCT/JP2005/023637 filed on December 22, 2005 and as amended under PCT Article 19 on \_\_\_\_\_ (if any) and/or under PCT Article 34 on \_\_\_\_\_ (if any).

AND WHEREAS, TOKYO OHKA KOGYO CO., LTD., with its principal place of business at 150,  
Nakamaruko, Nakahara-ku, Kawasaki-shi, Kanagawa 211-0012 Japan, (hereinafter referred to as Assignee) desires to acquire the entire right, title, and interest in and to the said improvements with respect to the United States of America, its territories and possessions.

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, Assignor hereby acknowledges that it has sold, assigned, transferred and set over, and by these presents does hereby sell, assign, transfer and set over, unto Assignee, its successors, legal representatives and assigns, the entire right, title, and interest in the United States of America, and its territories and possessions in, to and under said improvements, and any Patent Applications in the United States of America and all divisions, renewals and continuations thereof, and all Patents of the United States of America which may be granted thereon and all reissues and extensions thereof, and all rights of priority under International Conventions; and Assignor hereby authorizes and requests the Commissioner of Patents of the United States of America to issue all Patents for said improvements to Assignee, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND ASSIGNOR HEREBY covenants and agrees that it will communicate to Assignee, its successors, legal representatives and assigns, any facts known to it respecting said improvements, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said improvements in the United States of America.

IN TESTIMONY WHEREOF, Assignor intending to be legally bound has hereunto affixed its signature.

This 24<sup>th</sup> day of May, 2007

Keita Ishiduka  
Signature of first inventor: Keita ISHIDUKA

Signature of Witness: \_\_\_\_\_

Printed Name of Witness: \_\_\_\_\_

This 25 day of May, 2007

Kotaro Endo  
Signature of second inventor: Kotaro ENDO

Signature of Witness: \_\_\_\_\_

Printed Name of Witness: \_\_\_\_\_